

Title (en)
POWER MODULE

Title (de)
LEISTUNGSMODUL

Title (fr)
MODULE D'ALIMENTATION

Publication
EP 4327360 A1 20240228 (EN)

Application
EP 22723288 A 20220421

Priority

- US 202117239418 A 20210423
- US 2022025680 W 20220421

Abstract (en)
[origin: WO2022226142A1] The present disclosure describes a power module having a substrate, first and second pluralities of vertical power devices, and first and second terminal assemblies. The substrate has a top surface with a first trace and a second trace. The first plurality of vertical power devices and the second plurality of vertical power devices are electrically coupled to form part of a power circuit. The first plurality of vertical power devices is electrically and mechanically directly coupled between the first trace and a bottom of a first elongated bar of the first terminal assembly. The second plurality of vertical power devices are electrically and mechanically directly coupled between the second trace and a bottom of a second elongated bar of the second terminal assembly.

IPC 8 full level
H01L 23/495 (2006.01); **H01L 23/053** (2006.01); **H01L 23/31** (2006.01); **H02M 7/00** (2006.01); **H02M 7/5387** (2007.01)

CPC (source: EP)
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C-Set (source: EP)

1. **H01L 2224/85205** + **H01L 2924/00014**
2. **H01L 2224/85207** + **H01L 2924/00014**
3. **H01L 2924/00014** + **H01L 2224/45099**
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Designated contracting state (EPC)
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Designated extension state (EPC)
BA ME

Designated validation state (EPC)
KH MA MD TN

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